



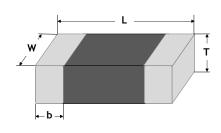
Surface Mount Multilayer Varistors High Voltage (HV) Series

Features:

- Bidirectional and symmetrical V/I characteristics Low Capacitance
- Meet IEC61000-4-2 Standard
- Large withstanding surge current capability 400~500A (@8/20μs)
- Multilayer construction provides higher power dissipation

Shape and Dimensions:

Unit (mm)	Length (L)	Width (W)	Thickness (T)	Termination bandwidth (b)
MLV3220HV240V0500			4 = 0.00	
MLV3220HV270V0500			1.7±0.30	
MLV3220HV390V0500	8.1±0.30	5.0±0.30		0.8 +0.5/-0.1
MLV3220HV430V0450			2.2±0.30	
MLV3220HV470V0400				



Product Identification:

MLV	3220	HV	270V	0500
Category Code	Size Code	Application Code	Breakdown Voltage Code	Surge Current Code
MLV = Multilayer Varistor	Inch (mm) 3220 (8153)	HV = High Voltage	390V = 390V 430V = 430V 470V = 470V	0400 = 400A 0450 = 450A 0500 = 500A

Electrical Characteristics:

Operating temperature: -55 to +85°C

Part Number	Size				Surge Current ³ @8/20µs (A)	Energy (J)	Capacitance⁴ @1kHz (pF)		
		Vac	Vdc	@1mA (V)	Α	V	<u>ш</u> ол гор з (A)	(0)	@1K12 (β1)
MLV3220HV240V0500		150	200	240 (±10%)		390	500	> 14.5	380
MLV3220HV270V0500		175	225	270 (±10%)		450	500	> 16.0	340
MLV3220HV390V0500	3220	250	330	390 (±10%)	10	647	500	> 20.0	125
MLV3220HV430V0450		275	369	430 (±10%)		705	450	> 21.0	120
MLV3220HV470V0400		300	385	470 (±10%)		775	400	> 21.6	115

¹ The breakdown voltage was measured at 1 mA current.

² The clamping voltage was measured at standard current 3220 (10A).

³ The surge current was tested at 8/20 µs waveform.

⁴ The capacitance value only for customer reference, it's not formal specification.

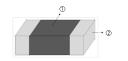




Surface Mount Multilayer Varistors High Voltage (HV) Series

Construction and Materials:

Body	Termination	
1	2	
ZnO	Ag/Ni/Sn	

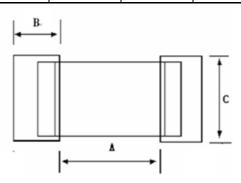


Packaging:

Chip Size	Parts on 7 inch (178mm) Reel	
3220	1,000	

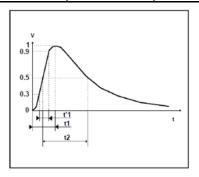
Recommended Foot Print Dimensions:

Size	A (mm)	B (mm)	C (mm)
3220	6.2~7.0	1.6~2.6	4.8~5.8



Surge Waveform:

Severity Level	t1 (=1.67t'1)	t2
1	8 µs	20 µs



Environmental Test:

Test item	Test condition	Requirement
High Temperature Storage	* Temperature : 125±2°C * Time : 1000±2 hours * Test after placing in ambient temperature for 24 hours	* Breakdown voltage change : within ±10% * No mechanical damage
High Temperature Storage	* Temperature : 125±2°C * Time : 1000±2 hours * Test after placing in ambient temperature for 24 hours	* Breakdown voltage change : within ±10% * No mechanical damage
High Temperature Storage	* Temperature : 125±2°C * Time : 1000±2 hours * Test after placing in ambient temperature for 24 hours	* Breakdown voltage change : within ±10% * No mechanical damage
High Temperature Load	* Temperature : 85±2°C * Rated working voltage applied * Time : 1000±2 hours * Test after placing in ambient temperature for 24 hours	* Breakdown voltage change : within ±10% * No mechanical damage
High Temperature Load	* Temperature : 85±2°C * Rated working voltage applied * Time : 1000±2 hours * Test after placing in ambient temperature for 24 hours	* Breakdown voltage change : within ±10% * No mechanical damage





Product Identification:

MLV 0402 ES 012V 0100 N T (1) (2) (3) (4) (5) (6) (7)

(1) Series Code:

MLV - Surface Mount Multilayer Varistor

MVA -- MLV Array

(2) Size Code:

Standard EIA Chip Size

(3) Application Code:

ES - Electro-static Discharge Protection

NA – Normal Surge Protection

HA – High Surge Protection

(4) Max. Working Voltage:

012V – 12 V

(5) Capacitance for ES Series:

0100 - 100 pF

02R5 - 2.5 pF

Peak Current for HA/NA Series: 0100 - 100 A

(6) Capacitance Tolerance for ES Series:

 $N - \pm 30\%$

P - Special

(7) Packaging Code:

T - Tape & Reel

Operating Temperatures:

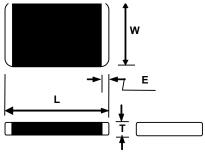
- -55°C to +85°C for size 0603 or smaller
- -55°C to +125°C for size 0805 or larger





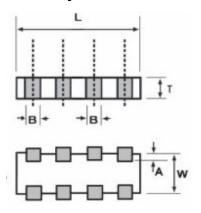
Shape and Dimensions:

MLV Series



	Size	L (mm)	W (mm)	T (mm)	E (mm)
	0201	0.60 ± 0.03	0.30 ± 0.03	0.30 ± 0.03	0.30 ± 0.03
	0402	1.00 ± 0.10	0.50 ± 0.10	0.50 ± 0.10	0.25 ± 0.10
	0603	1.60 ± 0.15	0.80 ± 0.15	0.90 max.	0.30 ± 0.10
	0805	2.00 ± 0.20	1.25 ± 0.15	1.00 max.	0.30 ± 0.10
)	1206	3.20 ± 0.20	1.60 ± 0.15	1.20 max.	0.50 ± 0.20
	1210	3.20 ± 0.20	2.50 ± 0.20	1.50 max.	0.50 ± 0.20
	1812	4.50 ± 0.20	3.20 ± 0.20	2.00 max.	0.60 ± 0.20
	2220	5.70 ± 0.20	5.00 ± 0.20	3.00 max.	0.60 ± 0.20

ESD Array



Size	0508	0612
L (mm)	2.00 ± 0.20	3.20 ± 0.20
W (mm)	1.25 ± 0.20	1.60 ± 0.15
T (mm)	0.80 max.	0.95 max.
A (mm)	0.20 ± 0.10	0.20 ± 0.10
B (mm)	0.25 ± 0.05	0.40 ± 0.15

Terms and Definitions:

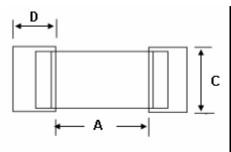
Term	Definition		
Max. Working Voltage	Maximum steady-state DC operating voltage with typical leakage current less than 50 μA at 25°C		
Varistor Voltage (BDV)	Breakdown DC voltage measured at current of 1 mA		
Max. Clamping Voltage	Maximum peak voltage across the part, measured at a specified pulse current and waveform		
Surge Current	Maximum peak current with the specified 8/20 µs waveform without damage		
Surge Shift △ V/V	The change of varistor voltage after applying the specified surge current		
Energy Absorption	Maximum energy dissipated with a specified 10/1000 μs waveform without damage		
Typical Capacitance	Capacitance measured with voltage bias less than 0.5 V _{RMS} at 1 KHz or 1 MHz		
Nonlinear Exponentα	$\alpha = (\log (V_{1mA}/V_{0.1mA}) / \log (I_{V1mA}/I_{V0.1mA}))$		
Leakage Current	Typical leakage current at 25 °C < 50 μA; Maximum leakage 200 μA.		
Cut-off Frequency	The frequency of -3 dB insertion loss		





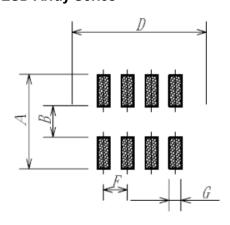
Recommended Land Patterns:

MLV Series



	Solder pad layout				
Size	A C (mm)		D (mm)		
0201	0.25~0.35	0.20~0.30	0.25~0.35		
0402	0.4~0.6	0.5~0.6	0.5~0.7		
0603	0.9~1.2	0.6~1.0	0.8~1.2		
0805	1.0~1.5	1.2~1.5	1.0~1.4		
1206	1.8~2.5	1.2~1.8	1.0~1.4		
1210	1.8~2.5	2.2~3.0	1.0~1.4		
1812	2.5~3.3	2.8~3.6	1.2~1.8		
2220	3.8~4.6	4.8~5.5	1.2~1.8		

ESD Array Series



Size	A (mm)	B (mm)	D (mm)	F (mm)	G (mm)
0508	2.10	0.40	2.50	0.50	0.35
0612	2.60	0.80	3.60	0.80	0.50





Environmental Tests:

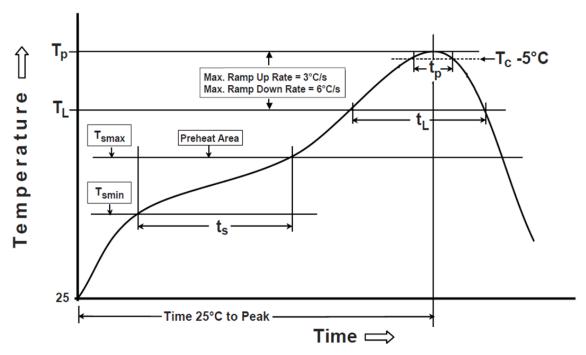
No.	Test	Requirement	Test condition	Test reference
1	Soldering heat resistance	BDV change ≤ ±10% No mechanical damage	One dip at 260°C for 5 sec.	MIL-STD-202 Method 210 IEC 60068-2-20
2	Solderability	New solder coverage ≥ 80%	One dip at 255°C for 5 sec. Non-active flux	MIL-STD-202 Method 208 IEC 60068-2-20
3	Maximum surge current	BDV change ≤ ±10% No mechanical damage	100 pulses of 8/20 µs with maximum surge current and 30 sec. interval at 25°C and 30 ~ 65% RH	CECC 42000 IEC 1051-1 Test 4.5
4	Maximum surge energy	BDV change ≤ ±10% No mechanical damage	100 pulses of 10/1000 μs with maximum surge current and 90 sec. interval at 25°C and 30 ~ 65% RH	CECC 42000
5	Thermal cycling	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	5 cycles between -40°C and 125°C with 30 min. dwell time at the temperature extremes and 60 min. dwell time at 25°C	CECC 42000 IEC 60068-2-14
6	Low temperature resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at -50°C	IEC 60068-2-1
7	Low temperature load resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at -50°C with working voltage applied	IEC 60068-2-1
8	High temperature resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at 150°C	MIL-STD-202 Method 108 CECC 42000
9	High temperature load resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	1000 hr at 85°C with working voltage applied	CECC 42000
10	Humidity resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	500 hr at 40°C and 90 ~ 95% RH	MIL-STD-202 Method 103 IEC 60068-2-3 CECC 42000;
11	Humidity load resistance	BDV change ≤ ±10% No mechanical damage Leakage current ≤ 200 µA	500 hr at 40°C and 90 ~ 95% RH with working voltage applied	MIL-STD-202 Method 103 IEC 60068-2-3 CECC 42000
12	ESD contact test*	Varistor voltage change > 115% working voltage	Contact electrostatic discharge 100 times with 1 second intervals at 8 KV (Level 4) and polarity: +,-	IEC 61000-4-2
13	ESD air test*	Varistor voltage change > 115% working voltage	Air contact electrostatic discharge 100 times with 1 second intervals at 15 KV (Level 4) and polarity:+,-	IEC 61000-4-2

^{*} For ES series only.





Soldering Temperature Profile:



Profile Feature	Pb-Free Assembly	
Preheat/Soak Temperature Min (T _{smin}) Temperature Max(T _{smax}) Time(t _s) from (T _{smin} to T _{smax})	150°C 200°C 60~120 seconds	
Ramp-uprate (T _L to T _p)	3°C/second max.	
$\begin{array}{c} \text{Liquidous temperature}(T_L) \\ \text{Time}(t_L) \text{ maintained above } T_L \end{array}$	217°C 60~150 seconds	
Peak package body temperature (T _p)	260°C	
Time $(t_p)^*$ within 5°C of the specified classification temperature (T_c)	30 seconds *	
Ramp-down rate (Tp to TL)	6°C/second max.	
Time 25°C to peak temperature	8 minutes max.	
* Tolerance for peak profile temperature (Tp) is defined	as a supplier minimum and a user maximum	





Disclaimer

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